IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under be international and Pan-American copyright conventions.			This level	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute				Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Informa	tion															
Company name*			Company un	Company unique ID			Unique ID Authority					Response Date*				
onsemi												2024-04-30				
Contact Name	Title - Contact			Pl	Phone - Contact*					Email - Contact*						
Product-Env-Steward	Product Enviro Compliance			N	NA					Product-Env-Stewards@onsemi.com						
Authorized Represent	Title - Representative			Pl	Phone - Representative*				Email - Representative*							
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com					
Requester I	uester Item Number Mfr Iten		n Number Mfr Item Name			I	Effective Da	te Vers	ion	Manufacturing Site		V	Weight*		UOM	Unit Typ
		ESD5581N2T5G		Bidirectional 5V mid-cap surge in SOD-882		D-882 2	2024-04-30 CN1		CN1		C	0.824 mg		Each		
Manufacturing Pr	roccess Informatio	n														
Terminal Pla	ninal Plating / Grid Array Material		Terminal Base Alloy J-S		-STD-020 MSL Rati	O MSL Rating		Peak Process Body Temperature		re Max Time at Peak Temper		Temperati	ire N	Number o	of Reflow Cyc	les
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy				260		С	30 seco		secono	is 3	3		
Comments																
evel 1 - maximum tim	ie at peak temperature	during sol	ldering is 10-3	0 seconds				·	·	·	·	·		·	·	
For more information	regarding material co	nposition	please refer to	page 3				•	·	•	·	·		·	·	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.015	mg	Supplier	Silicon (Si)	7440-21-3		0.015	mg
Die Attach	0.008	mg	Supplier	Silver (Ag)	7440-22-4		0.006	mg
			Supplier	Epoxy resins	129915-35-1		0.002	mg
Lead Frame	0.45	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0007	mg
			Supplier	Silicon (Si)	7440-21-3		0.0029	mg
			В	Nickel (Ni)	7440-02-0		0.0135	mg
			Supplier	Copper (Cu)	7440-50-8		0.4329	mg
Mold Compound-Black	0.34	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.0272	mg
_			Supplier	Carbon Black (C)	1333-86-4		0.0017	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0068	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.2941	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0102	mg
Plating	0.008	mg	Supplier	Palladium (Pd)	7440-05-3		0.0007	mg
			В	Nickel (Ni)	7440-02-0		0.0072	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Cu	0.003	mg	Supplier	Copper (Cu)	7440-50-8		0.003	mg